



PATENT
Atty. Docket: 10191/1466

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Volker BECKER, *et al.*
Serial No. : 09/581,663
Filed : August 3, 2000
For : METHOD FOR PROCESSING SILICON
BY ETCHING PROCESSES
Group Art Unit : 1746
Examiner : S. AHMED

MAILED

APR 15 2002

GROUP 1700

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Assistant Commissioner
for Patents
Washington D.C. 20231

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Date: 3/27, 2002

Reg. No. 36,197

Signature:

Jong H. Lee

AMENDMENT

Sir:

In response to the Office Action mailed December 21, 2001, the Applicants
respectfully submit the following amendments and remarks. The Applicants
respectfully request a one-month Extension of Time to respond to the Office Action.
The extended period expires on April 22, 2002, due to the one-month extended due
date falling on a Sunday.

04/22/2002 ASIN:LET-00000005-110600-02581663

IN THE CLAIMS:

01-FC:102

500.00 CH

02-FC:103

125.00 CH

Please cancel claims 1-31, without prejudice to the subject matter therein.

Please add the following new claims 32-69:

32. (New) A method for etching a silicon layered body, which has a first silicon layer (15) that is provided with an etching mask (10) for defining lateral recesses (21);

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